



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260204000.2
Qualification of RFAB wafer fab site for select devices
Change Notification / Sample Request

Date: February 04, 2026
To: Mouser PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Change Management Team
SC Business Services

20260204000.2
Attachment

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ISOM8116DFSRQ1	NULL
ISOM8113DFSRQ1	NULL
ISOM8115DFGRQ1	NULL
ISOM8111DFHRQ1	NULL
ISOM8115DFHRQ1	NULL
ISO7231CQDWRQ1	ISO7231CQDWRQ1
ISOM8115DFSRQ1	NULL
ISOM8110DFSRQ1	NULL
ISOM8111DFGRQ1	NULL
ISOM8118DFGRQ1	NULL
ISOM8110DFHRQ1	NULL
ISOM8118DFHRQ1	NULL
ISO7220AQDRQ1	ISO7220AQDRQ1
ISOM8113DFHRQ1	NULL
ISOM8118DFSRQ1	NULL
ISOM8110DFGRQ1	NULL
ISOM8111DFSRQ1	NULL
ISOM8113DFGRQ1	NULL
ISOM8117DFGRQ1	NULL
ISOM8117DFHRQ1	NULL
ISOM8112DFHRQ1	NULL
ISOM8117DFSRQ1	NULL
ISOM8112DFSRQ1	NULL
ISO7240CFQDWRQ1	ISO7240CFQDWRQ1
ISOM8116DFGRQ1	NULL
ISOM8112DFGRQ1	NULL
ISOM8116DFHRQ1	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260204000.2	PCN Date:	February 04, 2026
Title:	Qualification of RFAB wafer fab site for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	August 03, 2026	Sample requests accepted until:	April 05, 2026*

***Sample requests received after April 05, 2026 will not be supported.**

Change Type:

<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Material
<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Process
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input checked="" type="checkbox"/> Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Material
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB using the ISOSAX qualified process technology for the devices listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
MIHO	ISOSAX	200 mm	RFAB	ISOSAX	300 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Supply continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

No impact on Form, Fit, Function, Quality or Reliability.

Review the standard data packet (SDP) for comparison.

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change			

Changes to product identification resulting from this PCN:

**Fab Site
Information:**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
MIHO	MH8	JPN	Ibaraki
RFAB	RFB	USA	Richardson

Sample product shipping label (not actual product label):



Product Affected

ISO722QDRQ1	ISO721QDRQ1	ISO7220AQDRQ1	ISO7221AQDRQ1
ISO7221CQDRQ1	ISO7231CQDWRQ1	ISO7240CFQDWRQ1	ISO7241CQDWRQ1
ISO7242CQDWRQ1	ISOM8110DFGRQ1	ISOM8110DFHRQ1	ISOM8110DFSRQ1
ISOM8111DFGRQ1	ISOM8113DFGRQ1	ISOM8115DFSRQ1	ISOM8117DFHRQ1
ISOM8111DFHRQ1	ISOM8113DFHRQ1	ISOM8116DFGRQ1	ISOM8117DFSRQ1
ISOM8111DFSRQ1	ISOM8113DFSRQ1	ISOM8116DFHRQ1	ISOM8118DFGRQ1
ISOM8112DFGRQ1	ISOM8115DFGRQ1	ISOM8116DFSRQ1	ISOM8118DFHRQ1
ISOM8112DFHRQ1	ISOM8115DFHRQ1	ISOM8117DFGRQ1	ISOM8118DFSRQ1
ISOM8112DFSRQ1			

Product Attributes

Attributes		Qual Device: ISO7221CQDRQ1	QBS Package Reference: AMC22C12QDRQ1	QBS Process Reference: LM70880QRRXRQ1	QBS Product Reference: ISO7220AQDRQ1	QBS Package, Product Reference: ISO7221CQDRQ1	QBS Product Reference: ISO7221AQDRQ1
Automotive Grade Level		Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)		-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function		Interface	Signal Chain	Power Management	Interface	Interface	Interface
Wafer Fab Supplier		RFAB, RFAB, RFAB	MH8, DMOS6	CFAB, CFAB, RFAB	RFAB, RFAB, MH8	RFAB, RFAB, MH8	RFAB, RFAB, MH8
Assembly Site		MLA	MLA	CLARK-AT	MLA	MLA	MLA
Package Group		SOIC	SOIC	QFN	SOIC	SOIC	SOIC
Package Designator		D	D	RRX	D	D	D
Pin Count		8	8	29	8	8	8

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device ISO7221CQDRQ1 is qualified at MSL1 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISO7221CQDRQ1	QBS Package Reference: AMC22C12QDRQ1	QBS Process Reference: LM70880QRRXRQ1	QBS Product Reference: ISO7220AQDRQ1	QBS Package, Product Reference: ISO7221CQDRQ1	QBS Product Reference: ISO7221AQDRQ1
Test Group A - Accelerated Environment Stress Tests													

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISO7221CQDRQ1	QBS Package Reference: AMC22C12QDRQ1	QBS Process Reference: LM70880QRRXRQ1	QBS Product Reference: ISO7220AQDRQ1	QBS Package, Product Reference: ISO7221CQDRQ1	QBS Product Reference: ISO7221AQDRQ1
PC	A1	JEDEC J-STD-020 JEDEC22-A113	3	77	Preconditioning	MSL1 260C	-	No Fails	-	-	-	No Fails	-
PC	A1	JEDEC J-STD-020 JEDEC22-A113	3	77	Preconditioning	MSL2 260C	-	-	No Fails	-	-	-	-
HAST	A2	JEDEC JEDEC22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	-	-	-
AC/UHAST	A3	JEDEC JEDEC22-A102/JEDEC JEDEC22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	-	-	-	1/77/0	-
AC/UHAST	A3	JEDEC JEDEC22-A102/JEDEC JEDEC22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	-	-	-	-
TC	A4	JEDEC JEDEC22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	1/77/0	-
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	-	-	-	1/5/0	-
TC-SAM	A4	-	3	3	Post TC SAM	<50% delamination	-	-	-	-	-	1/12/0	-
HTSL	A6	JEDEC JEDEC22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	-	-	-	-
Test Group B - Accelerated Lifetime Simulation Tests													
HTOL	B1	JEDEC JEDEC22-A108	3	77	Life Test	125C	1000 Hours	-	-	3/231/0	-	-	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	1230C	48 Hours	-	-	3/2400/0	-	-	-
Test Group C - Package Assembly Integrity Tests													
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	-	-	3/90/0	-

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: IS07221CQDRQ1	QBS Package Reference: AMC22C12QDRQ1	QBS Process Reference: LM70880QRXRQ1	QBS Product Reference: IS07220AQDRQ1	QBS Package, Product Reference: IS07221CQDRQ1	QBS Product Reference: IS07221AQDRQ1
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	-	-	3/90/0	-
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	1/15/0	-	-	-	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	1/15/0	-	-	-	-
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	3/30/0	-	-	3/30/0	-
Test Group D - Die Fabrication Reliability Tests													
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests													
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	1/3/0	-	1/3/0	1/3/0	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	-	1/3/0	-	1/3/0	1/3/0	1/3/0
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	-	1/6/0	-	1/3/0	1/3/0	1/3/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	1/30/0	1/30/0	1/30/0
Additional Tests													

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

- Grade 0 (or E) : -40C to +150C
- Grade 1 (or Q) : -40C to +125C
- Grade 2 (or T) : -40C to +105C
- Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

- Room/Hot/Cold : HTOL, ED
- Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
- Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2511-001

Q006 SOIC at MLA Approve Date 20-January-2026

Attributes		Qual Device: ISOM8110DFGRQ1	QBS Package Reference: TLV9022QDRQ1
Automotive Grade Level		Grade 1	Grade 1
Operating Temp Range (C)		-40 to 125	-40 to 125
Product Function		Interface	Signal Chain
Wafer Fab Supplier		RFAB, RFAB, RFAB	RFAB
Assembly Site		MLA	MLA
Package Group		SOIC	SOIC
Package Designator		DFG	D
Pin Count		4	8

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISOM8110DFGRQ1	QBS Reference: TLV9022QDRQ1
Test Group A - Accelerated Environment Stress Tests									
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	-	No Fails
PC	A1.1	-	3	22	SAM Precon Pre	Review for delamination	-	-	3/66/0
PC	A1.2	-	3	22	SAM Precon Post	Review for delamination	-	-	3/66/0
HAST	A2.1	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	3/231/0
HAST	A2.1.2	-	3	1	Cross Section, post bHAST, 1X	Post stress cross section	Completed	-	3/3/0
HAST	A2.1.3	-	3	3	Wire Bond Shear, post bHAST, 1X	Post stress	-	-	3/9/0
HAST	A2.1.4	-	3	3	Bond Pull over Stitch, post bHAST, 1X	Post stress	-	-	3/9/0
HAST	A2.1.5	-	3	3	Bond Pull over Ball, post bHAST, 1X	Post stress	-	-	3/9/0
HAST	A2.2	JEDEC JESD22-A110	3	70	Biased HAST	130C/85%RH	192 Hours	-	3/231/0
HAST	A2.2.1	-	3	22	SAM Analysis, post bHAST 2X	Review for delamination	Completed	-	3/66/0
HAST	A2.2.2	-	3	1	Cross Section, post bHAST, 2X	Post stress cross section	Completed	-	3/3/0
HAST	A2.2.3	-	3	3	Wire Bond Shear, post bHAST, 2X	Post stress	-	-	3/9/0
HAST	A2.2.4	-	3	3	Bond Pull over Stitch, post bHAST, 2X	Post stress	-	-	3/9/0
HAST	A2.2.5	-	3	3	Bond Pull over Ball, post bHAST, 2X	Post stress	-	-	3/9/0
TC	A4.1	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0
TC	A4.1.1	-	3	22	SAM Analysis, post TC 1X	Review for delamination	Completed	-	3/66/0

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISOM8110DFGRQ1	QBS Reference: TLV9022QDRQ1
TC	A4.1.2	-	3	1	Cross Section, post TC, 1X	Post stress cross section	Completed	-	3/3/0
TC	A4.1.3	-	3	3	Wire Bond Shear, post TC, 1X	Post stress	-	-	3/9/0
TC	A4.1.4	-	3	3	Bond Pull over Stitch, post TC, 1X	Post stress	-	-	3/9/0
TC	A4.1.5	-	3	3	Bond Pull over Ball, post TC, 1X	Post stress	-	-	3/9/0
TC	A4.2	JEDEC JESD22-A104 and Appendix 3	3	70	Temperature Cycle	-65C/150C	1000 Cycles	-	3/231/0
TC	A4.2.1	-	3	22	SAM Analysis, post TC, 2X	Review for delamination	Completed	-	3/66/0
TC	A4.2.2	-	3	1	Cross Section, post TC, 2X	Post stress cross section	Completed	-	3/3/0
TC	A4.2.3	-	3	3	Wire Bond Shear, post TC, 2X	Post stress	-	-	3/9/0
TC	A4.2.4	-	3	3	Bond Pull over Stitch, post TC, 2X	Post stress	-	-	3/9/0
TC	A4.2.5	-	3	3	Bond Pull over Ball, post TC, 2X	Post stress	-	-	3/9/0
HTSL	A6.1	JEDEC JESD22-A103	3	45	High Temperature Storage Life	150C	1000 Hours	-	3/135/0
HTSL	A6.2	JEDEC JESD22-A103	3	44	High Temperature Storage Life	150C	2000 Hours	-	3/135/0
HTSL	A6.2.1	-	3	1	Cross Section, post HTSL, 2X	Post stress cross section	Completed	-	3/3/0
Test Group C - Package Assembly Integrity Tests									
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device ISOM8110DFGRQ1 is qualified at MSL2 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

- Grade 0 (or E): -40C to +150C
- Grade 1 (or Q): -40C to +125C
- Grade 2 (or T): -40C to +105C
- Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

- Room/Hot/Cold : HTOL, ED
- Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
- Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2310-080

Product Attributes

Attributes		Qual Device: <u>ISOM8110DFGRQ1</u>	QBS Package Reference: <u>TLV9022QDRQ1</u>	QBS Process Reference: <u>TCAN1044AEVDRQ1</u>	QBS Product Reference: <u>ISOM8110DFGRQ1</u>
Automotive Grade Level		Grade 1	Grade 1	Grade 0	Grade 1
Operating Temp Range (C)		-40 to 125	-40 to 125	-40 to 150	-40 to 125
Product Function		Interface	Signal Chain	Interface	Interface
Wafer Fab Supplier		RFAB, RFAB, RFAB	RFAB	RFAB	RFAB, RFAB, MH8
Assembly Site		MLA	MLA	MLA	MLA
Package Group		SOIC	SOIC	SOIC	SOIC
Package Designator		DFG	D	D	DFG
Pin Count		4	8	8	4

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device ISOM8110DFGRQ1 is qualified at MSL2 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: <u>ISOM8110DFGRQ1</u>	QBS Package Reference: <u>TLV9022QDRQ1</u>	QBS Process Reference: <u>TCAN1044AEVDRQ1</u>	QBS Product Reference: <u>ISOM8110DFGRQ1</u>

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISOM8110DFGRQ1	QBS Package Reference: TLV9022QDRQ1	QBS Process Reference: TCAN1044AEVDRQ1	QBS Product Reference: ISOM8110DFGRQ1
Test Group A - Accelerated Environment Stress Tests											
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	-	No Fails	-	-
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	No Fails	-	-	No Fails
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	-	1/77/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	-	-	1/77/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	-	-
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	-	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	-	-	1/5/0
TC-SAM	A4	-	3	3	Post TC SAM	<50% delamination	-	-	-	-	3/36/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	1/45/0	3/135/0	-	1/45/0
Test Group B - Accelerated Lifetime Simulation Tests											
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	-	-	1/77/0

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISOM8110DFGRQ1	QBS Package Reference: TLV9022QDRQ1	QBS Process Reference: TCAN1044AEVDRQ1	QBS Product Reference: ISOM8110DFGRQ1
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	1000 Hours	-	-	3/231/0	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	150C	48 Hours	-	-	3/2400/0	-
Test Group C - Package Assembly Integrity Tests											
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	-	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	-	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	1/15/0	-	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	1/15/0	-	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	3/30/0	3/30/0	-	3/30/0
Test Group D - Die Fabrication Reliability Tests											
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDBB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISOM8110DFGRQ1	QBS Package Reference: TLV9022QDRQ1	QBS Process Reference: TCAN1044AEVDRQ1	QBS Product Reference: ISOM8110DFGRQ1
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests											
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	-	-	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	-	-	-	1/3/0
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	-	-	-	1/3/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	3/90/0

Additional Tests

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

- Grade 0 (or E): -40C to +150C
- Grade 1 (or Q): -40C to +125C
- Grade 2 (or T): -40C to +105C
- Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

- Room/Hot/Cold : HTOL, ED
- Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
- Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2310-080

ZVEI ID: SEM-PW-02, SEM-PW-13

For alternate parts with similar or improved performance, please visit the product page on TI.com

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

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